UNIVERSITE PAUL SABATIER TOULOUSE III

TDs
Systèmes électroniques non linéaires

DATASHEET

Datasheet AD7520
Datasheet DAC0800

Intervenants Cours / TDs /TPs :
Leymarie H. // Camps T.// Perisse T.

Bibliographie :

- *Principes de conversions* *Jean-Paul Troadec* *Dunod*
- *Acquisition de données* *Georges Asch* *Dunod*
- *Traitement des signaux et acquisition de données (cours et exercices résolus)* *Francis Cottet* *Dunod.*
- *Techniques de l'ingénieur* *Claude Prévot* *E370, E371, E372.*

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10-Bit, 12-Bit, Multiplying D/A Converters

The AD7520 and AD7521 are monolithic, high accuracy, low cost 10-bit and 12-bit resolution, multiplying digital-to-analog converters (DAC). Intersil's thin-film on CMOS processing gives up to 10-bit accuracy with TTL/CMOS compatible operation. Digital inputs are fully protected against static discharge by diodes to ground and positive supply.

Typical applications include digital/analog interfacing, multiplication and division, programmable power supplies, CRT character generation, digitally controlled gain circuits, integrators and attenuators, etc.

Features

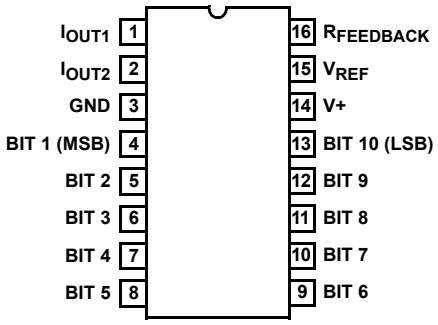
- AD7520, 10-Bit Resolution; 8-Bit Linearity
- AD7521, 12-Bit Resolution; 10-Bit Linearity
- Low Power Dissipation (Max). 20mW
- Low Nonlinearity Tempco at 2ppm of FSR/^{O}C
- Current Settling Time to 0.05% of FSR 1.0µs
- Supply Voltage Range . . . . . ±5V to +15V
- TTL/CMOS Compatible
- Full Input Static Protection

Ordering Information

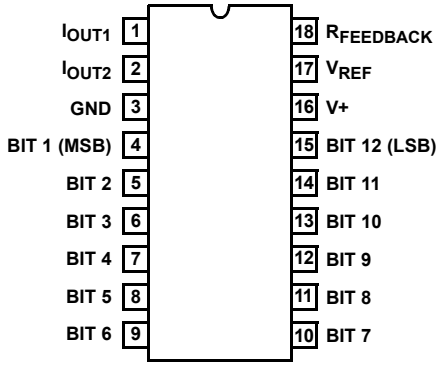
PART NUMBER	LINEARITY (INL, DNL)	TEMP. RANGE (^{O}C)	PACKAGE	PKG. NO.
AD7520JN	0.2% (8-Bit)	0 to 70	16 Ld PDIP	E16.3
AD7521LN	0.05% (10-Bit)	0 to 70	18 Ld PDIP	E18.3

Pinouts

AD7520 (PDIP)
TOP VIEW



AD7521 (PDIP)
TOP VIEW



Absolute Maximum Ratings

Supply Voltage (V+ to GND) . . . . . .+17V
V_{REF} . . . . . ±25V
Digital Input Voltage Range . . . . . V+ to GND
Output Voltage Compliance . . . . . .-100mV to V+

Operating Conditions

Temperature Ranges
JN, LN Versions . . . . . 0^oC to 70^oC

Thermal Information

Thermal Resistance (Typical, Note 1)	θ_{JA} ($^oC/W$)	θ_{JC} ($^oC/W$)
16 Ld PDIP Package	90	N/A
18 Ld PDIP Package	80	N/A

Maximum Junction Temperature (Plastic Packages) . . . . . 150^oC
Maximum Storage Temperature Range . . . . . -65^oC to 150^oC
Maximum Lead Temperature (Soldering 10s) . . . . . 300^oC

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

The digital control inputs are zener protected; however, permanent damage may occur on unconnected units under high energy electrostatic fields. Keep unused units in conductive foam at all times.

Do not apply voltages higher than V_{DD} or less than GND potential on any terminal except V_{REF} and $R_{FEEDBACK}$.

1. θ_{JA} is measured with the component mounted on a low effective thermal conductivity test board in free air. See Tech Brief TB379 for details.

Electrical Specifications

V+ = +15V, V_{REF} = +10V, T_A = 25^oC Unless Otherwise Specified

PARAMETER		TEST CONDITIONS	AD7520 MIN	AD7520 TYP	AD7520 MAX	AD7521 MIN	AD7521 TYP	AD7521 MAX	UNITS
SYSTEM PERFORMANCE (Note 2)									
Resolution			10	10	10	12	12	12	Bits
Nonlinearity	J	(Note 3) (Figure 2) $-10V \le V_{REF} \le +10V$	-	-	±0.2 (8-Bit)	-	-	-	% of FSR
	L	$-10V \le V_{REF} \le +10V$ (Figure 2)	-	-	±0.05 (10-Bit)	-	-	±0.05 (10-Bit)	% of FSR
Nonlinearity Tempco		$-10V \le V_{REF} \le +10V$ (Notes 3, 4)	-	-	±2	-	-	±2	ppm of FSR/^oC
Gain Error			-	±0.3	-	-	±0.3	-	% of FSR
Gain Error Tempco			-	-	±10	-	-	±10	ppm of FSR/^oC
Output Leakage Current (Either Output)		Over the Specified Temperature Range	-	-	±200	-	-	±200	nA
DYNAMIC CHARACTERISTICS									
Output Current Settling Time		To 0.05% of FSR (All Digital Inputs Low To High And High To Low) (Note 4) (Figure 7)	-	1.0	-	-	1.0	-	µs
Feedthrough Error		V_{REF} = $20V_{P-P}$, 100kHz All Digital Inputs Low (Note 4) (Figure 6)	-	-	10	-	-	10	mV_{P-P}
REFERENCE INPUT									
Input Resistance		All Digital Inputs High I_{OUT1} at Ground	5	10	20	5	10	20	kΩ
ANALOG OUTPUT									
Output Capacitance	I_{OUT1}	All Digital Inputs High (Note 4) (Figure 5)	-	200	-	-	200	-	pF
	I_{OUT2}		-	75	-	-	75	-	pF
	I_{OUT1}	All Digital Inputs Low (Note 4) (Figure 5)	-	75	-	-	75	-	pF
	I_{OUT2}		-	200	-	-	200	-	pF
Output Noise		Both Outputs (Note 4) (Figure 4)	-	Equivalent to 10kΩ	-	-	Equivalent to 10kΩ	-	Johnson Noise
DIGITAL INPUTS									
Low State Threshold, V_{IL}		Over the Specified Temperature Range V_{IN} = 0V or +15V	-	-	0.8	-	-	0.8	V
High State Threshold, V_{IH}			2.4	-	-	2.4	-	-	V
Input Current, I_{IL}, I_{IH}			-	-	±1	-	-	±1	µA
Input Coding		See Tables 1 and 2	Binary/Offset Binary						

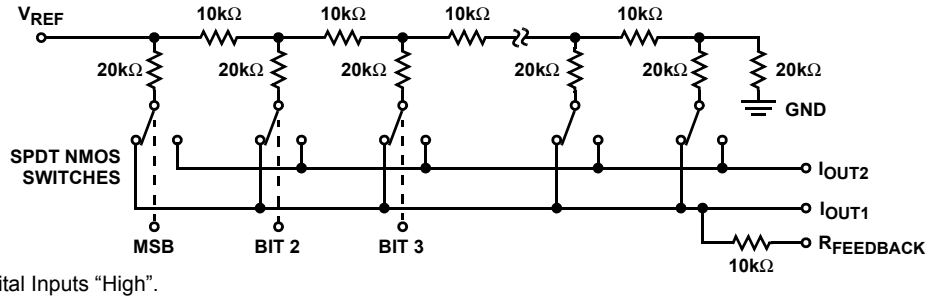
Electrical Specifications V+ = +15V, V_{REF} = +10V, T_A = 25°C Unless Otherwise Specified **(Continued)**

PARAMETER	TEST CONDITIONS	AD7520			AD7521			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
POWER SUPPLY CHARACTERISTICS								
Power Supply Rejection	V+ = 14.5V to 15.5V (Note 3) (Figure 3)	-	±0.005	-	-	±0.005	-	% FSR/% ΔV+
Power Supply Voltage Range		+5 to +15			+5 to +15			V
I+	All Digital Inputs at 0V or V+ Excluding Ladder Network	-	±1	-	-	±1	-	µA
	All Digital Inputs High or Low Excluding Ladder Network	-	-	2	-	-	2	mA
Total Power Dissipation	Including the Ladder Network	-	20	-	-	20	-	mW

NOTES:

2. Full Scale Range (FSR) is 10V for Unipolar and ±10V for Bipolar modes.
3. Using internal feedback resistor $R_{FEEDBACK}$.
4. Guaranteed by design, or characterization and not production tested.
5. Accuracy not guaranteed unless outputs at GND potential.
6. Accuracy is tested and guaranteed at V+ = 15V only.

Functional Diagram



NOTES:

Switches shown for Digital Inputs “High”.
Resistor values are typical.

Pin Descriptions

AD7520	AD7521	PIN NAME	DESCRIPTION
1	1	I_{OUT1}	Current Out summing junction of the R2R ladder network.
2	2	I_{OUT2}	Current Out virtual ground, return path for the R2R ladder network.
3	3	GND	Digital Ground. Ground potential for digital side of D/A.
4	4	Bits 1(MSB)	Most Significant Digital Data Bit.
5	5	Bit 2	Digital Bit 2.
6	6	Bit 3	Digital Bit 3.
7	7	Bit 4	Digital Bit 4.
8	8	Bit 5	Digital Bit 5.
9	9	Bit 6	Digital Bit 6.
10	10	Bit 7	Digital Bit 7.
11	11	Bit 8	Digital Bit 8.
12	12	Bit 9	Digital Bit 9.
13	13	Bit 10	Digital Bit 10 (AD7521). Least Significant Digital Data Bit (AD7520).
-	14	Bit 11	Digital Bit 11 (AD7521).
-	15	Bit 12	Least Significant Digital Data Bit (AD7521).
14	16	V+	Power Supply +5V to +15V.
15	17	V_{REF}	Voltage Reference Input to set the output range. Supplies the R2R resistor ladder.
16	18	$R_{FEEDBACK}$	Feedback resistor used for the current to voltage conversion when using an external Op Amp.

Definition of Terms

Nonlinearity: Error contributed by deviation of the DAC transfer function from a “best straight line” through the actual plot of transfer function. Normally expressed as a percentage of full scale range or in (sub)multiples of 1 LSB.

Resolution: It is addressing the smallest distinct analog output change that a D/A converter can produce. It is commonly expressed as the number of converter bits. A converter with resolution of N bits can resolve output changes of 2^{-N} of the full-scale range, e.g., 2^{-N} V_{REF} for a unipolar conversion. Resolution by no means implies linearity.

Settling Time: Time required for the output of a DAC to settle to within specified error band around its final value (e.g., $^1/_2$ LSB) for a given digital input change, i.e., all digital inputs LOW to HIGH and HIGH to LOW.

Gain Error: The difference between actual and ideal analog output values at full scale range, i.e., all digital inputs at HIGH state. It is expressed as a percentage of full scale range or in (sub)multiples of 1 LSB.

Feedthrough Error: Error caused by capacitive coupling from V_{REF} to I_{OUT1} with all digital inputs LOW.

Output Capacitance: Capacitance from I_{OUT1} and I_{OUT2} terminals to ground.

Output Leakage Current: Current which appears on I_{OUT1} terminal when all digital inputs are LOW or on I_{OUT2} terminal when all digital inputs are HIGH.

Detailed Description

The AD7520 and AD7521 are monolithic, multiplying D/A converters. A highly stable thin film R-2R resistor ladder network and NMOS SPDT switches form the basis of the converter circuit, CMOS level shifters permit low power TTL/CMOS compatible operation. An external voltage or current reference and an operational amplifier are all that is required for most voltage output applications.

A simplified equivalent circuit of the DAC is shown in the *Functional Diagram*. The NMOS SPDT switches steer the ladder leg currents between I_{OUT1} and I_{OUT2} buses which must be held either at ground potential. This configuration maintains a constant current in each ladder leg independent of the input code.

Converter errors are further reduced by using separate metal interconnections between the major bits and the outputs. Use of high threshold switches reduce offset (leakage) errors to a negligible level.

The level shifter circuits are comprised of three inverters with positive feedback from the output of the second to the first, see Figure 1. This configuration results in TTL/CMOS compatible operation over the full military temperature range. With the ladder SPDT switches driven by the level shifter, each switch is binarily weighted for an ON resistance proportional to the respective ladder leg current. This assures a constant voltage drop across each switch, creating equipotential terminations for the 2R ladder resistors and highly accurate leg currents.

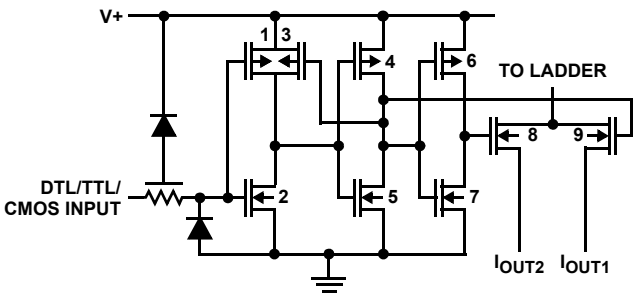


FIGURE 1. CMOS LEVEL SHIFTER AND SWITCH

Test Circuits

The following test circuits apply for the AD7520. Similar circuits are used for the AD7521.

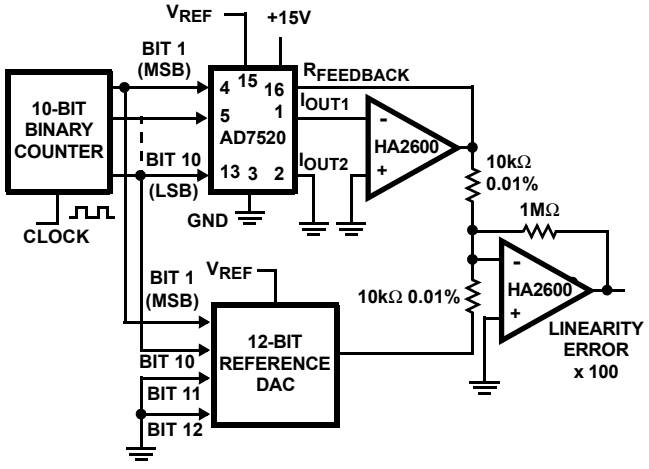


FIGURE 2. NONLINEARITY

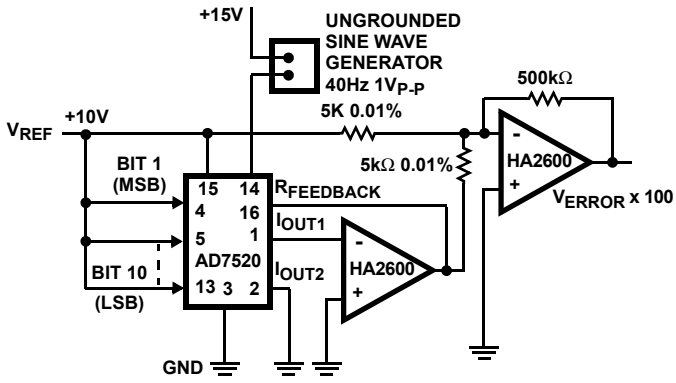


FIGURE 3. POWER SUPPLY REJECTION

Test Circuits The following test circuits apply for the AD7520. Similar circuits are used for the AD7521. **(Continued)**

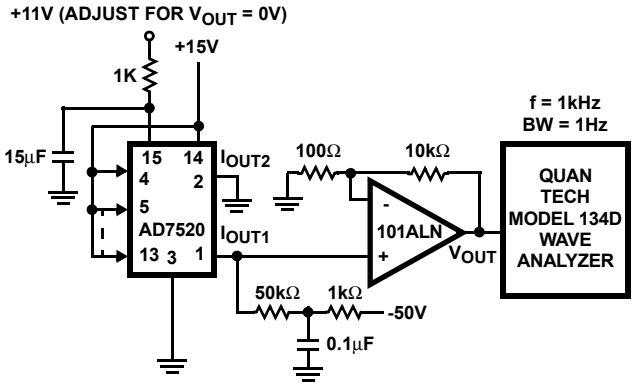


FIGURE 4. NOISE

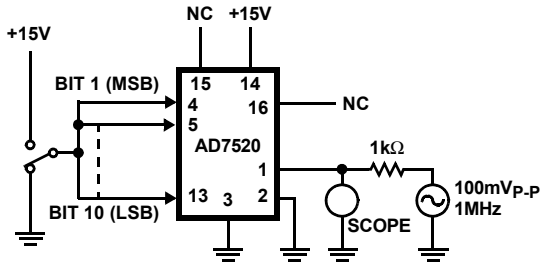


FIGURE 5. OUTPUT CAPACITANCE

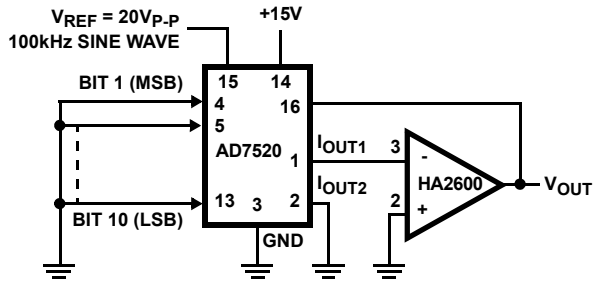


FIGURE 6. FEEDTHROUGH ERROR

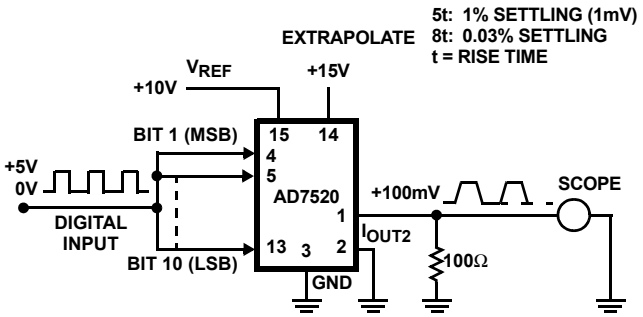


FIGURE 7. OUTPUT CURRENT SETTLING TIME

Applications

Unipolar Binary Operation

The circuit configuration for operating the AD7520 in unipolar mode is shown in Figure 8. Similar circuits can be used for AD7521. With positive and negative V_{REF} values the circuit is capable of 2-Quadrant multiplication. The *Digital Input Code/Analog Output Value* table for unipolar mode is given in Table 1.

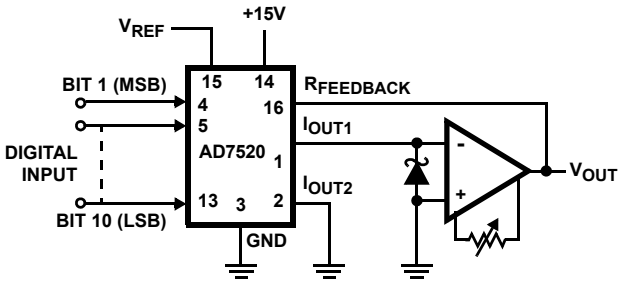


FIGURE 8. UNIPOLAR BINARY OPERATION (2-QUADRANT MULTIPLICATION)

TABLE 1. CODE TABLE - UNIPOLAR BINARY OPERATION

DIGITAL INPUT	ANALOG OUTPUT
1111111111	$-V_{REF}(1-2^{-N})$
1000000001	$-V_{REF}(1/2 + 2^{-N})$
1000000000	$-V_{REF}/2$
0111111111	$-V_{REF}(1/2-2^{-N})$
0000000001	$-V_{REF}(2^{-N})$
0000000000	0

NOTES:

1. LSB = 2^{-N} V_{REF}.
2. N = 8 for 7520
   N = 10 for 7521.

Zero Offset Adjustment

1. Connect all digital inputs to GND.
2. Adjust the offset zero adjust trimpot of the output operational amplifier for 0V at V_{OUT}.

Gain Adjustment

1. Connect all digital inputs to V+.
2. Monitor V_{OUT} for a $-V_{REF}(1-2^{-N})$ reading. (N = 8 for AD7520 and N = 10 for AD7521).

3. To decrease V_{OUT}, connect a series resistor (0 to 250Ω) between the reference voltage and the V_{REF} terminal.
4. To increase V_{OUT}, connect a series resistor (0 to 250Ω) in the I_{OUT1} amplifier feedback loop.

Bipolar (Offset Binary) Operation

The circuit configuration for operating the AD7520 in the bipolar mode is given in Figure 9. Similar circuits can be used for AD7521. Using offset binary digital input codes and positive and negative reference voltage values, 4-Quadrant multiplication can be realized. The "Digital Input Code/Analog Output Value" table for bipolar mode is given in Table 2.

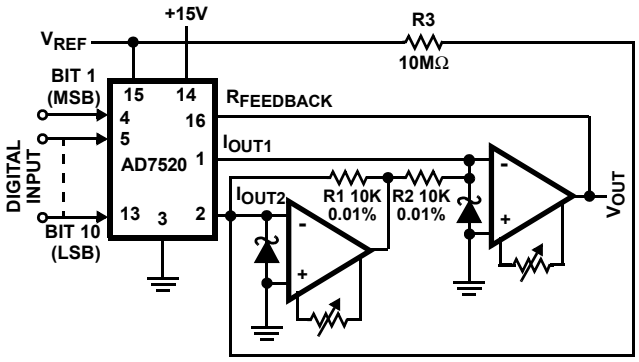


FIGURE 9. BIPOLAR OPERATION (4-QUADRANT MULTIPLICATION)

TABLE 2. BIPOLAR (OFFSET BINARY) CODE TABLE

DIGITAL INPUT	ANALOG OUTPUT
1111111111	$-V_{REF}(1-2^{-(N-1)})$
1000000001	$-V_{REF}(2^{-(N-1)})$
1000000000	0
0111111111	$V_{REF}(2^{-(N-1)})$
0000000001	$V_{REF}(1-2^{-(N-1)})$
0000000000	V_{REF}

NOTES:

1. LSB = $2^{-(N-1)}$ V_{REF}.
2. N = 8 for 7520
   N = 10 for 7521.

A "Logic 1" input at any digital input forces the corresponding ladder switch to steer the bit current to IOUT1 bus. A "Logic 0" input forces the bit current to IOUT2 bus. For any code the IOUT1 and IOUT2 bus currents are complements of one another. The current amplifier at IOUT2 changes the polarity of IOUT2 current and the transconductance amplifier at IOUT1 output sums the two currents. This configuration doubles the output range. The difference current resulting at zero offset binary code, (MSB = "Logic 1", all other bits = "Logic 0"), is corrected by using an external resistor, (10MW), from VREF to IOUT2 .

Offset Adjustment

1. Adjust V_{REF} to approximately +10V.
2. Connect all digital inputs to "Logic 1".
3. Adjust I_{OUT2} amplifier offset adjust trimpot for 0V ±1mV at I_{OUT2} amplifier output.
4. Connect MSB (Bit 1) to "Logic 1" and all other bits to "Logic 0".
5. Adjust I_{OUT1} amplifier offset adjust trimpot for 0V ±1mV at V_{OUT}.

Gain Adjustment

1. Connect all digital inputs to V+.
2. Monitor V_{OUT} for a $-V_{REF}(1-2^{-(N-1)})$ volts reading. (N = 8 for AD7520, and N = 10 for AD7521.).
3. To increase V_{OUT}, connect a series resistor of up to 250Ω between V_{OUT} and $R_{FEEDBACK}$.
4. To decrease V_{OUT}, connect a series resister of up to 250Ω between the reference voltage and the V_{REF} terminal.

Die Characteristics

DIE DIMENSIONS:

101 mils x 103 mils (2565µm x 2616µm)

METALLIZATION:

Type: Pure Aluminum
Thickness: 10 ±1kÅ

PASSIVATION:

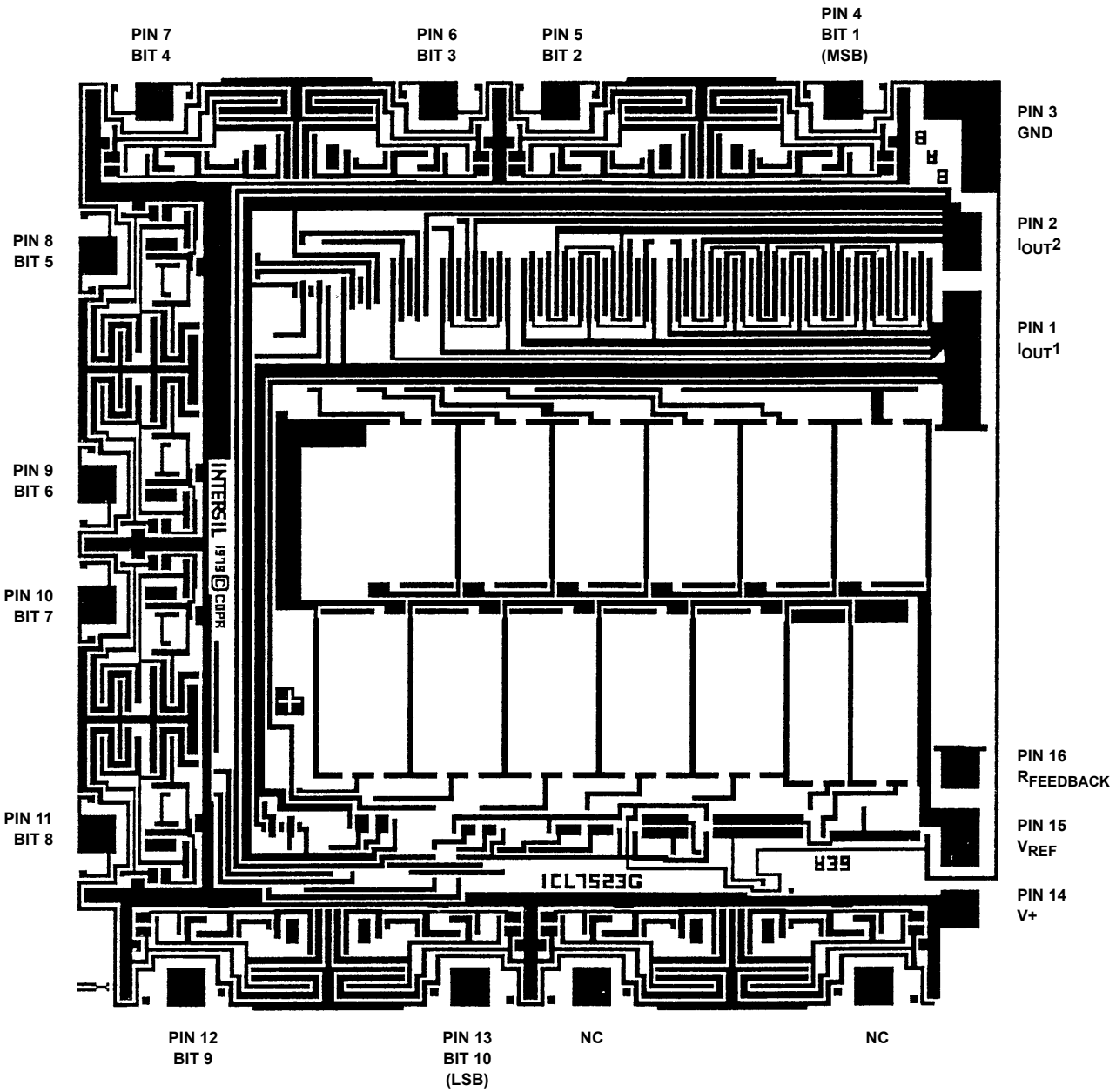
Type: PSG/Nitride
PSG: 7 ±1.4kÅ
Nitride: 8 ±1.2kÅ

PROCESS:

CMOS Metal Gate

Metallization Mask Layout

AD7520



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Type: Pure Aluminum
Thickness: 10 ±1kÅ

PASSIVATION:

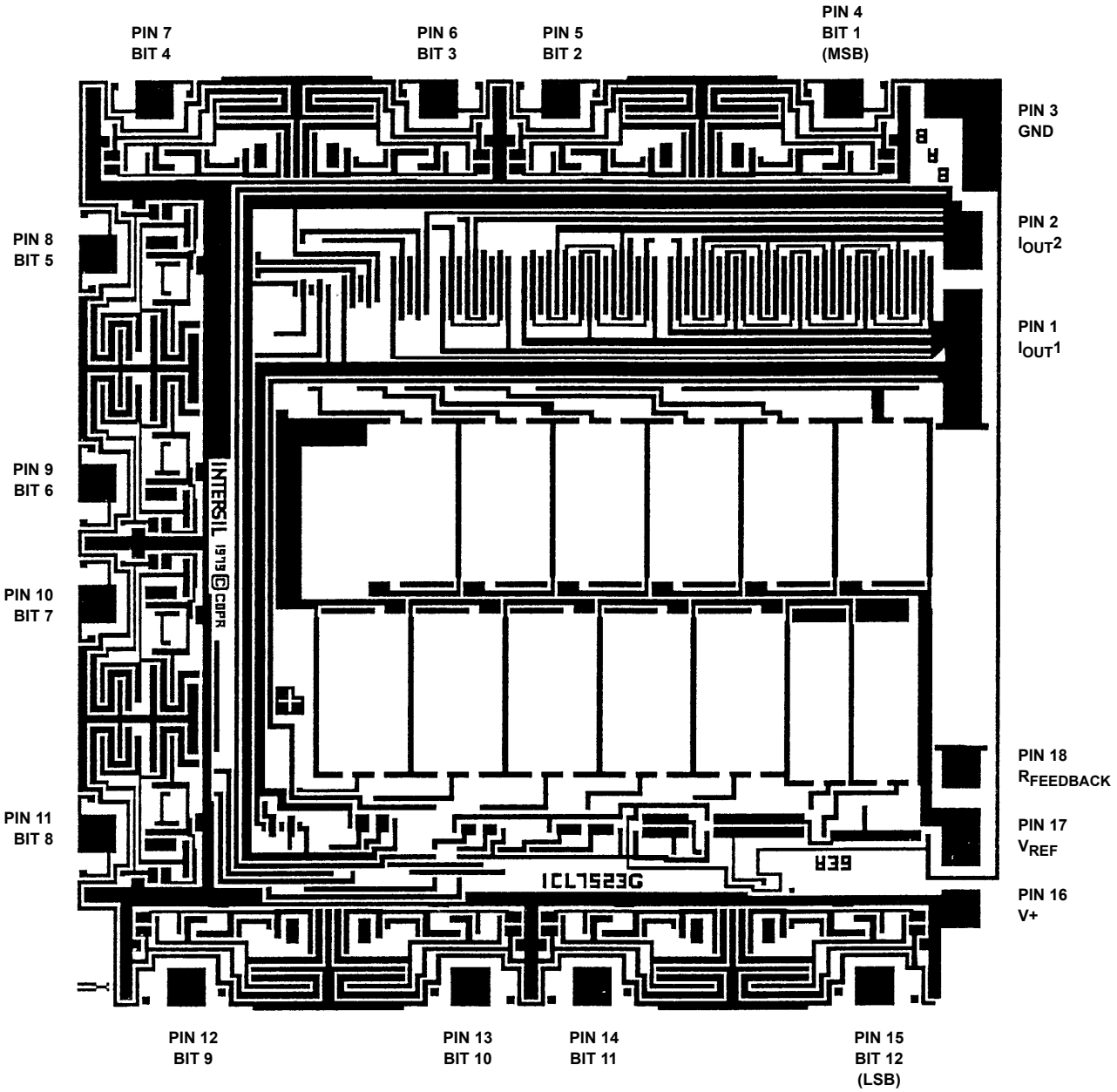
Type: PSG/Nitride
PSG: 7 ±1.4kÅ
Nitride: 8 ±1.2kÅ

PROCESS:

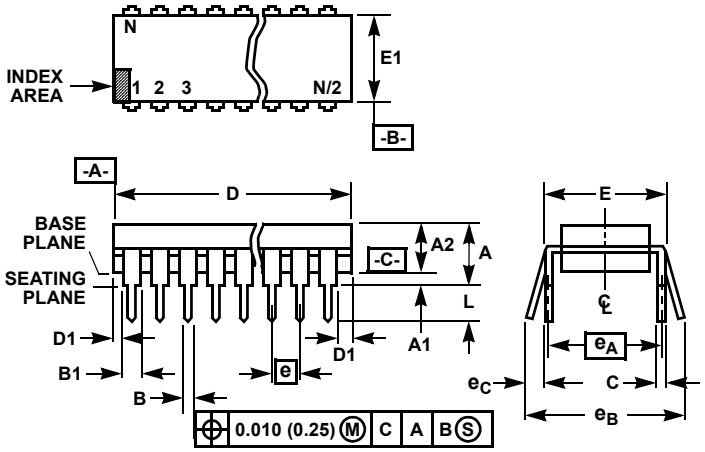
CMOS Metal Gate

Metallization Mask Layout

AD7521



Dual-In-Line Plastic Packages (PDIP)



NOTES:

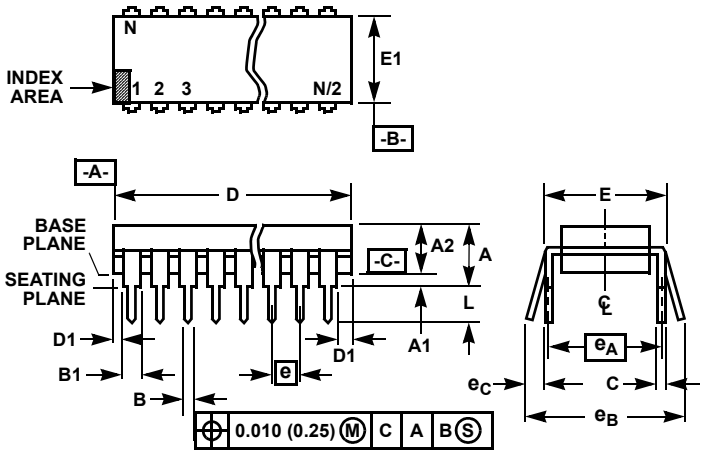
1. Controlling Dimensions: INCH. In case of conflict between English and Metric dimensions, the inch dimensions control.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Symbols are defined in the “MO Series Symbol List” in Section 2.2 of Publication No. 95.
4. Dimensions A, A1 and L are measured with the package seated in JEDEC seating plane gauge GS-3.
5. D, D1, and E1 dimensions do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010 inch (0.25mm).
6. E and e_A are measured with the leads constrained to be perpendicular to datum -C-.
7. e_B and e_C are measured at the lead tips with the leads unconstrained. e_C must be zero or greater.
8. B1 maximum dimensions do not include dambar protrusions. Dambar protrusions shall not exceed 0.010 inch (0.25mm).
9. N is the maximum number of terminal positions.
10. Corner leads (1, N, N/2 and N/2 + 1) for E8.3, E16.3, E18.3, E28.3, E42.6 will have a B1 dimension of 0.030 - 0.045 inch (0.76 - 1.14mm).

E16.3 (JEDEC MS-001-BB ISSUE D)
16 LEAD DUAL-IN-LINE PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	-	0.210	-	5.33	4
A1	0.015	-	0.39	-	4
A2	0.115	0.195	2.93	4.95	-
B	0.014	0.022	0.356	0.558	-
B1	0.045	0.070	1.15	1.77	8, 10
C	0.008	0.014	0.204	0.355	-
D	0.735	0.775	18.66	19.68	5
D1	0.005	-	0.13	-	5
E	0.300	0.325	7.62	8.25	6
E1	0.240	0.280	6.10	7.11	5
e	0.100 BSC		2.54 BSC		-
e_A	0.300 BSC		7.62 BSC		6
e_B	-	0.430	-	10.92	7
L	0.115	0.150	2.93	3.81	4
N	16		16		9

Rev. 0 12/93

Dual-In-Line Plastic Packages (PDIP)



NOTES:

1. Controlling Dimensions: INCH. In case of conflict between English and Metric dimensions, the inch dimensions control.
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9. N is the maximum number of terminal positions.
10. Corner leads (1, N, N/2 and N/2 + 1) for E8.3, E16.3, E18.3, E28.3, E42.6 will have a B1 dimension of 0.030 - 0.045 inch (0.76 - 1.14mm).

E18.3 (JEDEC MS-001-BC ISSUE D)
18 LEAD DUAL-IN-LINE PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	-	0.210	-	5.33	4
A1	0.015	-	0.39	-	4
A2	0.115	0.195	2.93	4.95	-
B	0.014	0.022	0.356	0.558	-
B1	0.045	0.070	1.15	1.77	8, 10
C	0.008	0.014	0.204	0.355	-
D	0.845	0.880	21.47	22.35	5
D1	0.005	-	0.13	-	5
E	0.300	0.325	7.62	8.25	6
E1	0.240	0.280	6.10	7.11	5
e	0.100 BSC		2.54 BSC		-
e_A	0.300 BSC		7.62 BSC		6
e_B	-	0.430	-	10.92	7
L	0.115	0.150	2.93	3.81	4
N	18		18		9

Rev. 0 12/93

National Semiconductor

January 1995

DAC0800/DAC0801/DAC0802 8-Bit Digital-to-Analog Converters

General Description

The DAC0800 series are monolithic 8-bit high-speed current-output digital-to-analog converters (DAC) featuring typical settling times of 100 ns. When used as a multiplying DAC, monotonic performance over a 40 to 1 reference current range is possible. The DAC0800 series also features high compliance complementary current outputs to allow differential output voltages of 20 Vp-p with simple resistor loads as shown in *Figure 1*. The reference-to-full-scale current matching of better than ±1 LSB eliminates the need for full-scale trims in most applications while the nonlinearities of better than ±0.1% over temperature minimizes system error accumulations.

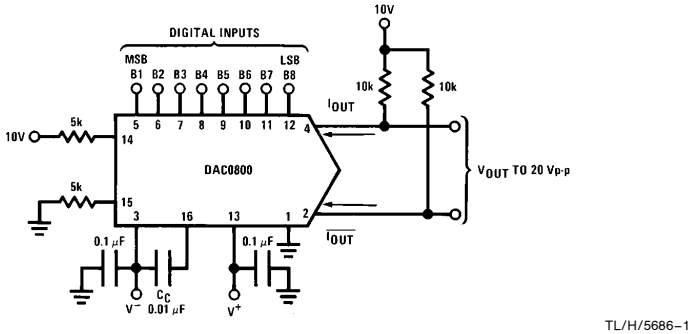
The noise immune inputs of the DAC0800 series will accept TTL levels with the logic threshold pin, V_{LC}, grounded. Changing the V_{LC} potential will allow direct interface to other logic families. The performance and characteristics of the device are essentially unchanged over the full ±4.5V to ±18V power supply range; power dissipation is only 33 mW with ±5V supplies and is independent of the logic input states.

The DAC0800, DAC0802, DAC0800C, DAC0801C and DAC0802C are a direct replacement for the DAC-08, DAC-08A, DAC-08C, DAC-08E and DAC-08H, respectively.

Features

- Fast settling output current — 100 ns
- Full scale error — ±1 LSB
- Nonlinearity over temperature — ±0.1%
- Full scale current drift — ±10 ppm/°C
- High output compliance — −10V to +18V
- Complementary current outputs
- Interface directly with TTL, CMOS, PMOS and others
- 2 quadrant wide range multiplying capability
- Wide power supply range — ±4.5V to ±18V
- Low power consumption — 33 mW at ±5V
- Low cost

Typical Applications



TL/H/5686–1

FIGURE 1. ±20 V_{P-P} Output Digital-to-Analog Converter (Note 4)

Ordering Information

Non-Linearity	Temperature Range	Order Numbers				
		J Package (J16A)*		N Package (N16A)*		SO Package (M16A)
±0.1% FS	0°C ≤ T_A ≤ +70°C	DAC0802LCJ	DAC-08HQ	DAC0802LCN	DAC-08HP	DAC0802LCM
±0.19% FS	−55°C ≤ T_A ≤ +125°C	DAC0800LJ	DAC-08Q			
±0.19% FS	0°C ≤ T_A ≤ +70°C	DAC0800LCJ	DAC-08EQ	DAC0800LCN	DAC-08EP	DAC0800LCM
±0.39% FS	0°C ≤ T_A ≤ +70°C			DAC0801LCN	DAC-08CP	DAC0801LCM

*Devices may be ordered by using either order number.

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage ($V^+ - V^-$)	±18V or 36V
Power Dissipation (Note 2)	500 mW
Reference Input Differential Voltage (V14 to V15)	V^- to V^+
Reference Input Common-Mode Range (V14, V15)	V^- to V^+
Reference Input Current	5 mA
Logic Inputs	V^- to V^- plus 36V
Analog Current Outputs ($V_S^- = -15V$)	4.25 mA
ESD Susceptibility (Note 3)	TBD V
Storage Temperature	−65°C to +150°C

Lead Temp. (Soldering, 10 seconds)

Dual-In-Line Package (plastic)	260°C
Dual-In-Line Package (ceramic)	300°C
Surface Mount Package	
Vapor Phase (60 seconds)	215°C
Infrared (15 seconds)	220°C

Operating Conditions (Note 1)

	Min	Max	Units
Temperature (T_A)			
DAC0800L	−55	+125	°C
DAC0800LC	0	+70	°C
DAC0801LC	0	+70	°C
DAC0802LC	0	+70	°C

Electrical Characteristics

The following specifications apply for $V_S = \pm 15V$, $I_{REF} = 2$ mA and $T_{MIN} \le T_A \le T_{MAX}$ unless otherwise specified. Output characteristics refer to both I_{OUT} and $\overline{I_{OUT}}$.

Symbol	Parameter	Conditions	DAC0802LC			DAC0800L/ DAC0800LC			DAC0801LC			Units
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
	Resolution		8	8	8	8	8	8	8	8	8	Bits
	Monotonicity		8	8	8	8	8	8	8	8	8	Bits
	Nonlinearity				±0.1			±0.19			±0.39	%FS
t_s	Settling Time	To ±½ LSB, All Bits Switched "ON" or "OFF", $T_A = 25°C$		100	135					100	150	ns
		DAC0800L					100	135				ns
		DAC0800LC					100	150				ns
tPLH, tPHL	Propagation Delay	$T_A = 25°C$										
	Each Bit			35	60		35	60		35	60	ns
	All Bits Switched			35	60		35	60		35	60	ns
TCI_{FS}	Full Scale Tempco			±10	±50		±10	±50		±10	±80	ppm/°C
V_{OC}	Output Voltage Compliance	Full Scale Current Change <½ LSB, $R_{OUT} > 20$ MΩ Typ	−10		18	−10		18	−10		18	V
I_{FS4}	Full Scale Current	$V_{REF} = 10.000V$, R14 = 5.000 kΩ R15 = 5.000 kΩ, $T_A = 25°C$	1.984	1.992	2.000	1.94	1.99	2.04	1.94	1.99	2.04	mA
I_{FSS}	Full Scale Symmetry	$I_{FS4} - I_{FS2}$		±0.5	±4.0		±1	±8.0		±2	±16	μA
I_{ZS}	Zero Scale Current			0.1	1.0		0.2	2.0		0.2	4.0	μA
I_{FSR}	Output Current Range	$V^- = -5V$	0	2.0	2.1	0	2.0	2.1	0	2.0	2.1	mA
		$V^- = -8V$ to $-18V$	0	2.0	4.2	0	2.0	4.2	0	2.0	4.2	mA
	Logic Input Levels											
V_{IL}	Logic "0"	$V_{LC} = 0V$			0.8			0.8			0.8	V
V_{IH}	Logic "1"		2.0			2.0			2.0			V
	Logic Input Current	$V_{LC} = 0V$										
I_{IL}	Logic "0"	$-10V \le V_{IN} \le +0.8V$		−2.0	−10		−2.0	−10		−2.0	−10	μA
I_{IH}	Logic "1"	$2V \le V_{IN} \le +18V$		0.002	10		0.002	10		0.002	10	μA
V_{IS}	Logic Input Swing	$V^- = -15V$	−10		18	−10		18	−10		18	V
V_{THR}	Logic Threshold Range	$V_S = \pm 15V$	−10		13.5	−10		13.5	−10		13.5	V
I_{15}	Reference Bias Current			−1.0	−3.0		−1.0	−3.0		−1.0	−3.0	μA
dI/dt	Reference Input Slew Rate	*(Figure 12)*	4.0	8.0		4.0	8.0		4.0	8.0		mA/μs
$PSSI_{FS+}$	Power Supply Sensitivity	$4.5V \le V+ \le 18V$		0.0001	0.01		0.0001	0.01		0.0001	0.01	%/%
$PSSI_{FS-}$		$-4.5V \le V^- \le 18V$ $I_{REF} = 1$mA		0.0001	0.01		0.0001	0.01		0.0001	0.01	%/%
	Power Supply Current	$V_S = \pm 5V$, $I_{REF} = 1$ mA										
I+				2.3	3.8		2.3	3.8		2.3	3.8	mA
I−				−4.3	−5.8		−4.3	−5.8		−4.3	−5.8	mA
		$V_S = 5V$, $-15V$, $I_{REF} = 2$ mA										
I+				2.4	3.8		2.4	3.8		2.4	3.8	mA
I−				−6.4	−7.8		−6.4	−7.8		−6.4	−7.8	mA
		$V_S = \pm 15V$, $I_{REF} = 2$ mA										
I+				2.5	3.8		2.5	3.8		2.5	3.8	mA
I−				−6.5	−7.8		−6.5	−7.8		−6.5	−7.8	mA

Electrical Characteristics (Continued)

The following specifications apply for $V_S = \pm 15V$, $I_{REF} = 2$ mA and $T_{MIN} \leq T_A \leq T_{MAX}$ unless otherwise specified. Output characteristics refer to both I_{OUT} and $\overline{I_{OUT}}$.

Symbol	Parameter	Conditions	DAC0802LC			DAC0800L/ DAC0800LC			DAC0801LC			Units
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
P_D	Power Dissipation	$\pm 5V$, $I_{REF} = 1$ mA		33	48		33	48		33	48	mW
		5V, −15V, $I_{REF} = 2$ mA		108	136		108	136		108	136	mW
		$\pm 15V$, $I_{REF} = 2$ mA		135	174		135	174		135	174	mW

Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its specified operating conditions.

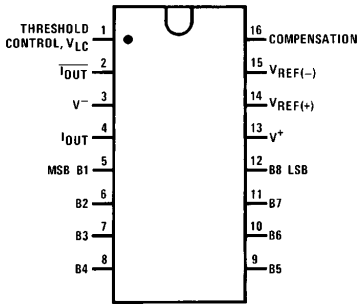
Note 2: The maximum junction temperature of the DAC0800, DAC0801 and DAC0802 is 125°C. For operating at elevated temperatures, devices in the Dual-In-Line J package must be derated based on a thermal resistance of 100°C/W, junction-to-ambient, 175°C/W for the molded Dual-In-Line N package and 100°C/W for the Small Outline M package.

Note 3: Human body model, 100 pF discharged through a 1.5 kΩ resistor.

Note 4: Pin-out numbers for the DAC080X represent the Dual-In-Line package. The Small Outline package pin-out differs from the Dual-In-Line package.

Connection Diagrams

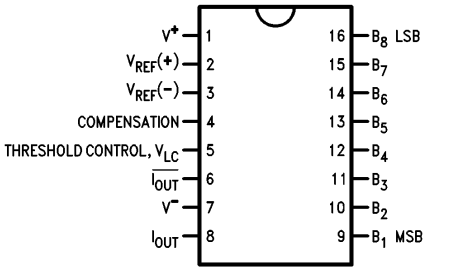
Dual-In-Line Package



TL/H/5686–13

Top View

Small Outline Package

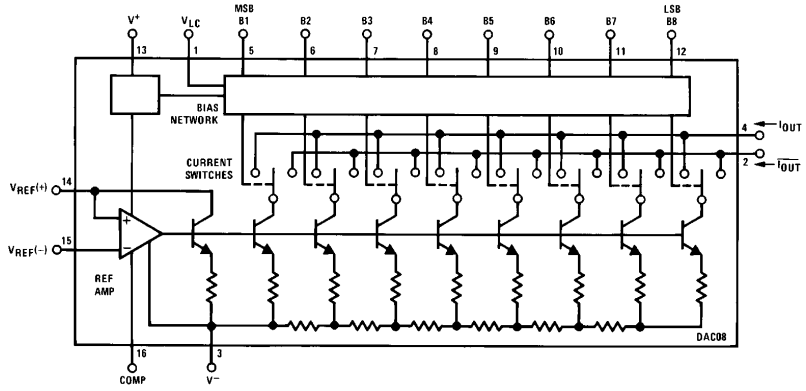


TL/H/5686–14

Top View

See Ordering Information

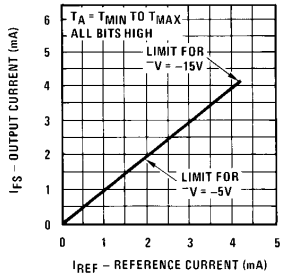
Block Diagram (Note 4)



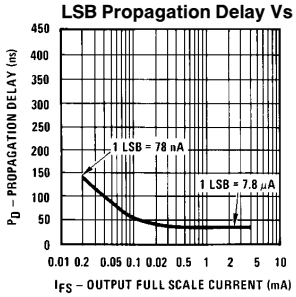
TL/H/5686–2

Typical Performance Characteristics

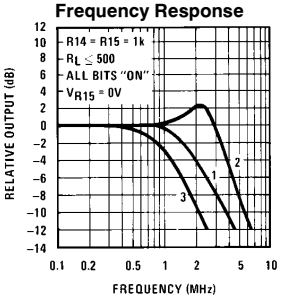
Full Scale Current vs Reference Current



LSB Propagation Delay Vs I_{FS}



Reference Input Frequency Response

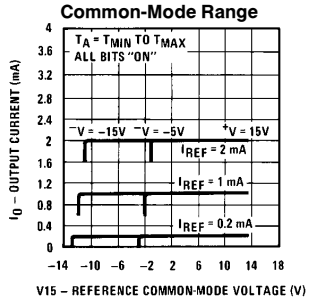


Curve 1: $C_C = 15$ pF, $V_{IN} = 2$ Vp-p centered at 1V.

Curve 2: $C_C = 15$ pF, $V_{IN} = 50$ mVp-p centered at 200 mV.

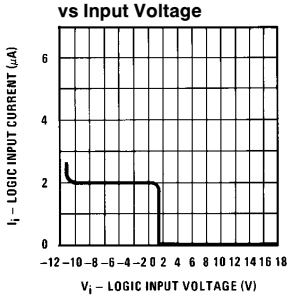
Curve 3: $C_C = 0$ pF, $V_{IN} = 100$ mVp-p at 0V and applied through 50 Ω connected to pin 14.2V applied to R14.

Reference Amp Common-Mode Range

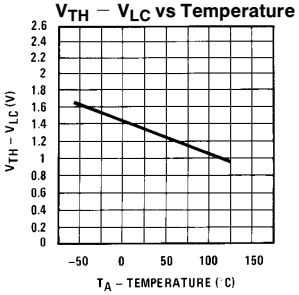


Note. Positive common-mode range is always (V+) − 1.5V

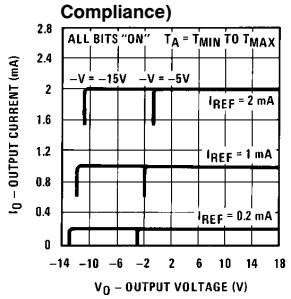
Logic Input Current vs Input Voltage



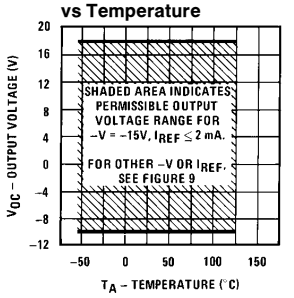
$V_{TH} - V_{LC}$ vs Temperature



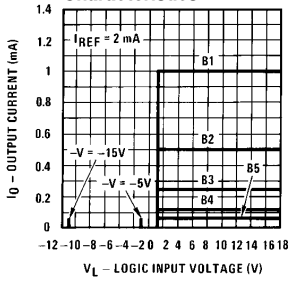
Output Current vs Output Voltage (Output Voltage Compliance)



Output Voltage Compliance vs Temperature



Bit Transfer Characteristics

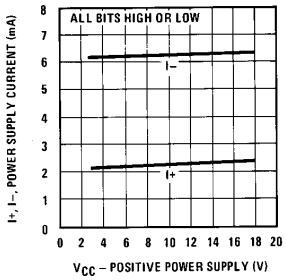


TL/H/5686–3

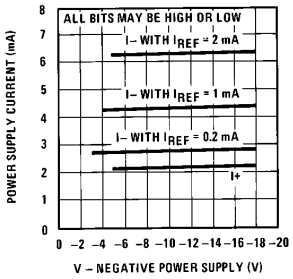
Note. B1–B8 have identical transfer characteristics. Bits are fully switched with less than ½ LSB error, at less than ±100 mV from actual threshold. These switching points are guaranteed to lie between 0.8 and 2V over the operating temperature range (V_{LC} = 0V).

Typical Performance Characteristics (Continued)

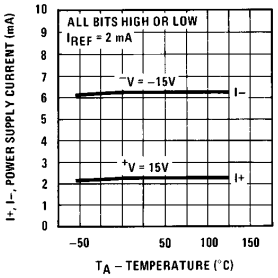
Power Supply Current vs $+V$



Power Supply Current vs $-V$

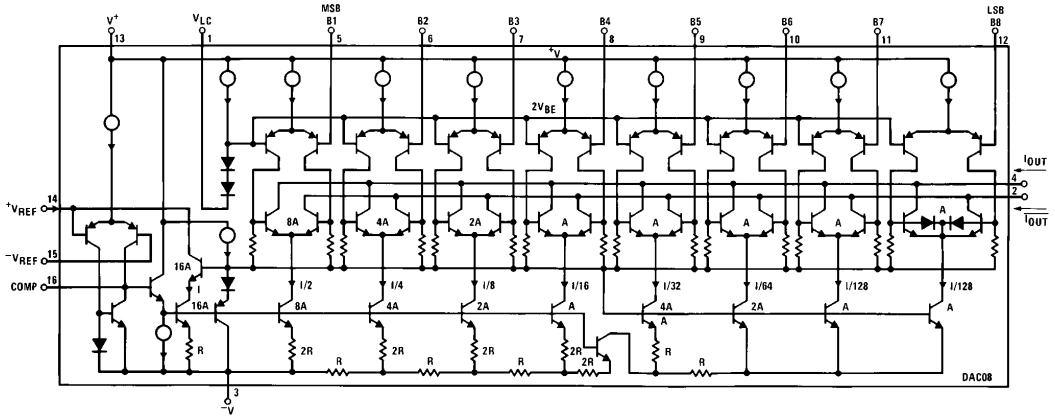


Power Supply Current vs Temperature



TL/H/5686–4

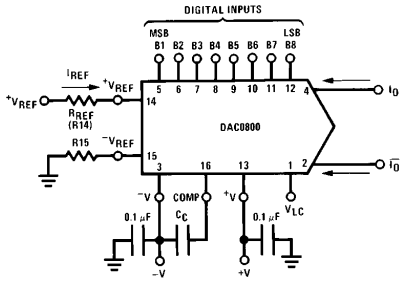
Equivalent Circuit



TL/H/5686–15

FIGURE 2

Typical Applications (Continued)



$$I_{FS} \approx \frac{+V_{REF}}{R_{REF}} \times \frac{255}{256}$$

$I_O + \overline{I_O} = I_{FS}$ for all logic states

For fixed reference, TTL operation, typical values are:

$V_{REF} = 10.000V$

$R_{REF} = 5.000k$

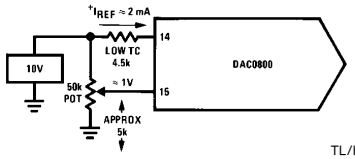
$R15 \approx R_{REF}$

$C_C = 0.01\ \mu F$

$V_{LC} = 0V$ (Ground)

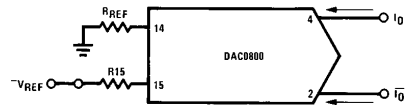
TL/H/5686–5

FIGURE 3. Basic Positive Reference Operation (Note 4)



TL/H/5686–21

FIGURE 4. Recommended Full Scale Adjustment Circuit (Note 4)



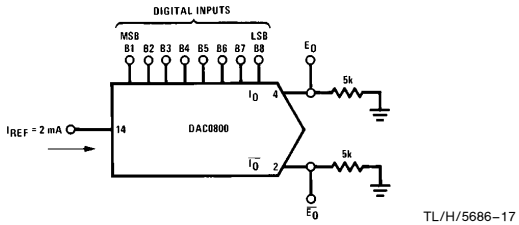
TL/H/5686–16

$$I_{FS} \approx \frac{-V_{REF}}{R_{REF}} \times \frac{255}{256}$$

Note. R_{REF} sets I_{FS}; R15 is for bias current cancellation

FIGURE 5. Basic Negative Reference Operation (Note 4)

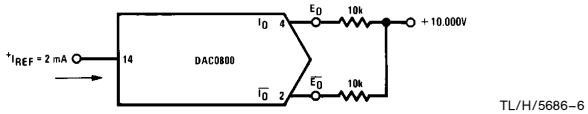
Typical Applications (Continued)



TL/H/5686–17

	B1	B2	B3	B4	B5	B6	B7	B8	I_O mA	$\overline{I_O}$ mA	E_O	$\overline{E_O}$
Full Scale	1	1	1	1	1	1	1	1	1.992	0.000	−9.960	0.000
Full Scale − LSB	1	1	1	1	1	1	1	0	1.984	0.008	−9.920	−0.040
Half Scale + LSB	1	0	0	0	0	0	0	1	1.008	0.984	−5.040	−4.920
Half Scale	1	0	0	0	0	0	0	0	1.000	0.992	−5.000	−4.960
Half Scale − LSB	0	1	1	1	1	1	1	1	0.992	1.000	−4.960	−5.000
Zero Scale + LSB	0	0	0	0	0	0	0	1	0.008	1.984	−0.040	−9.920
Zero Scale	0	0	0	0	0	0	0	0	0.000	1.992	0.000	−9.960

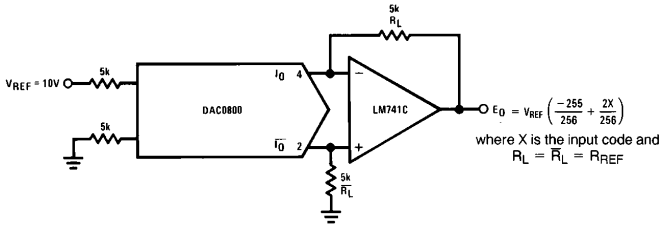
FIGURE 6. Basic Unipolar Negative Operation (Note 4)



TL/H/5686–6

	B1	B2	B3	B4	B5	B6	B7	B8	E_O	$\overline{E_O}$
Pos. Full Scale	1	1	1	1	1	1	1	1	−9.920	+10.000
Pos. Full Scale − LSB	1	1	1	1	1	1	1	0	−9.840	+9.920
Zero Scale + LSB	1	0	0	0	0	0	0	1	−0.080	+0.160
Zero Scale	1	0	0	0	0	0	0	0	0.000	+0.080
Zero Scale − LSB	0	1	1	1	1	1	1	1	+0.080	0.000
Neg. Full Scale + LSB	0	0	0	0	0	0	0	1	+9.920	−9.840
Neg. Full Scale	0	0	0	0	0	0	0	0	+10.000	−9.920

FIGURE 7. Basic Bipolar Output Operation (Note 4)



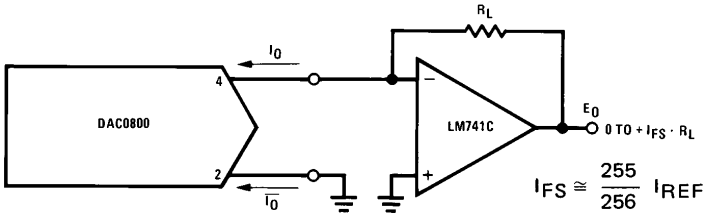
TL/H/5686–18

If $R_L = \overline{R_L}$ within ±0.05%, output is symmetrical about ground

	B1	B2	B3	B4	B5	B6	B7	B8	E_O
Pos. Full Scale	1	1	1	1	1	1	1	1	+9.960
Pos. Full Scale − LSB	1	1	1	1	1	1	1	0	+9.880
(+)Zero Scale	1	0	0	0	0	0	0	0	+0.040
(−)Zero Scale	0	1	1	1	1	1	1	1	−0.040
Neg. Full Scale + LSB	0	0	0	0	0	0	0	1	−9.880
Neg. Full Scale	0	0	0	0	0	0	0	0	−9.960

FIGURE 8. Symmetrical Offset Binary Operation (Note 4)

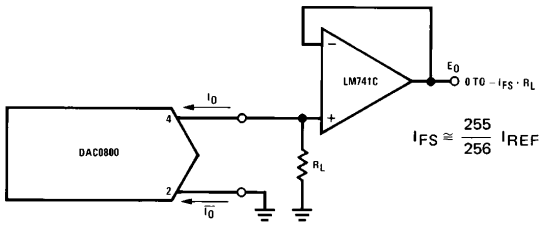
Typical Applications (Continued)



TL/H/5686–19

For complementary output (operation as negative logic DAC), connect inverting input of op amp to $\overline{I_O}$ (pin 2), connect I_O (pin 4) to ground.

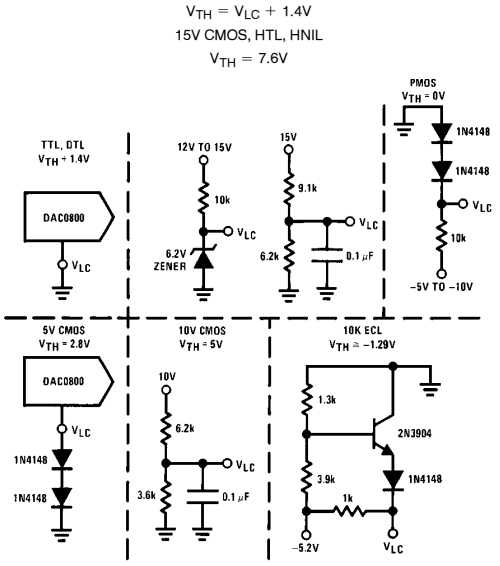
FIGURE 9. Positive Low Impedance Output Operation (Note 4)



TL/H/5686–20

For complementary output (operation as a negative logic DAC) connect non-inverting input of op am to $\overline{I_O}$ (pin 2); connect I_O (pin 4) to ground.

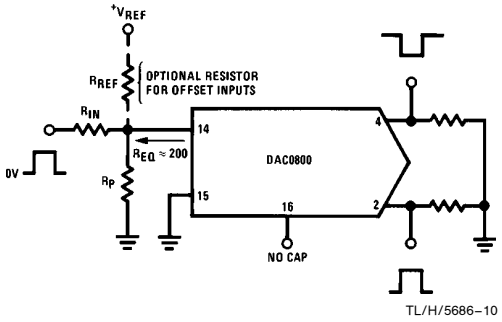
FIGURE 10. Negative Low Impedance Output Operation (Note 4)



TL/H/5686–9

Note. Do not exceed negative logic input range of DAC.

FIGURE 11. Interfacing with Various Logic Families

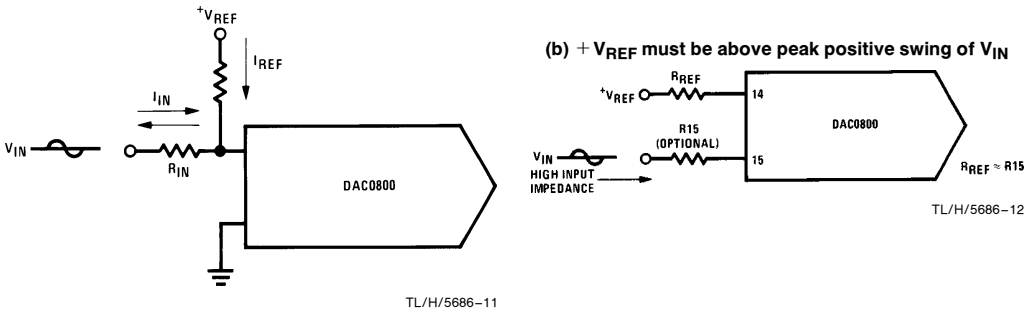


TL/H/5686–10

Typical values: $R_{IN} = 5k, +V_{IN} = 10V$

FIGURE 12. Pulsed Reference Operation (Note 4)

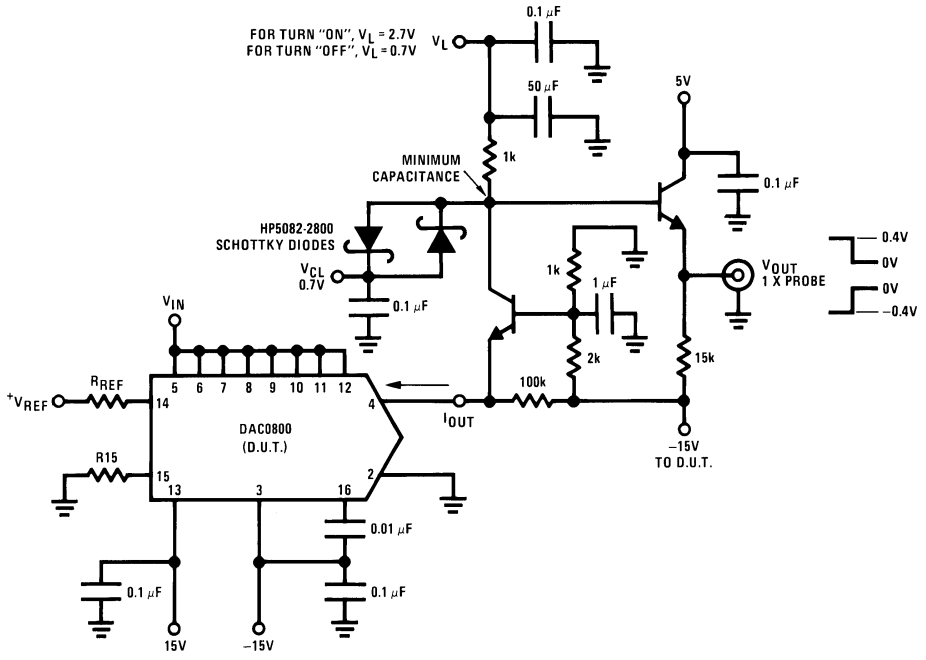
Typical Applications (Continued)



TL/H/5686–12

TL/H/5686–11

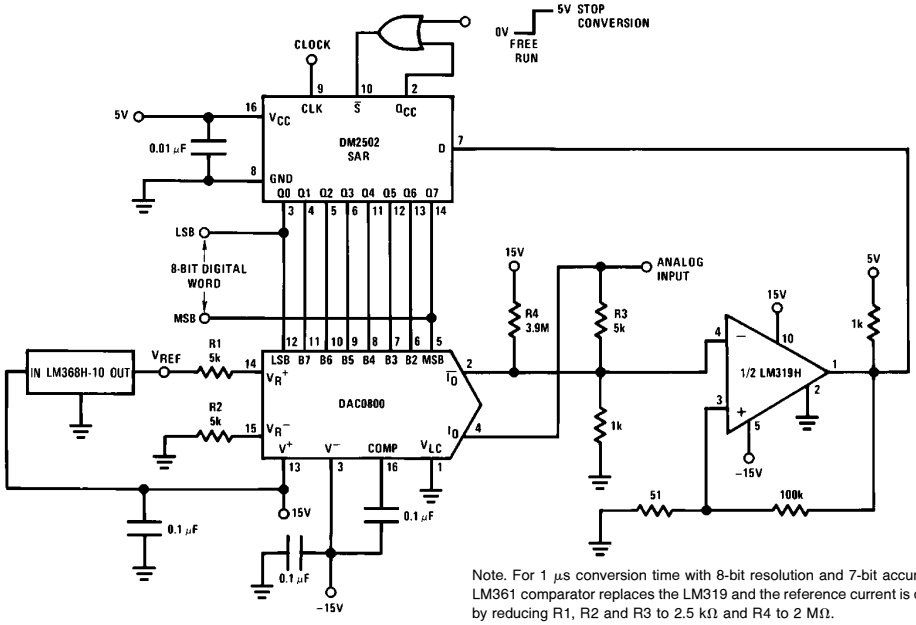
FIGURE 13. Accommodating Bipolar References (Note 4)



TL/H/5686–7

FIGURE 14. Settling Time Measurement (Note 4)

Typical Applications (Continued)

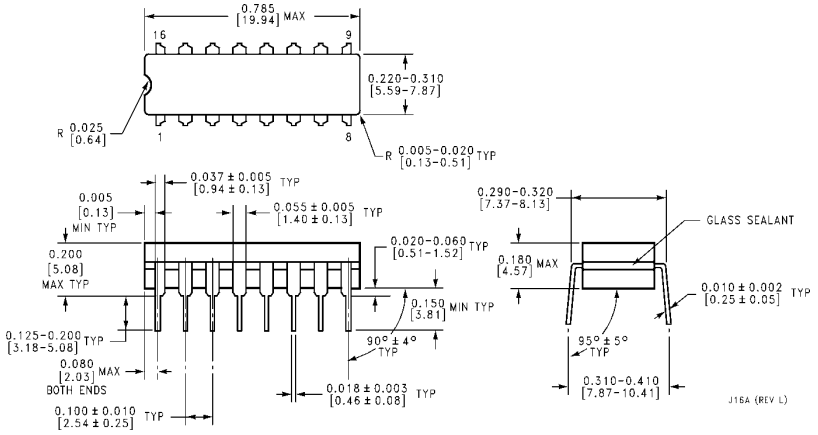


Note. For 1 μs conversion time with 8-bit resolution and 7-bit accuracy, an LM361 comparator replaces the LM319 and the reference current is doubled by reducing R1, R2 and R3 to 2.5 kΩ and R4 to 2 MΩ.

TL/H/5686–8

FIGURE 15. A Complete 2 μs Conversion Time, 8-Bit A/D Converter (Note 4)

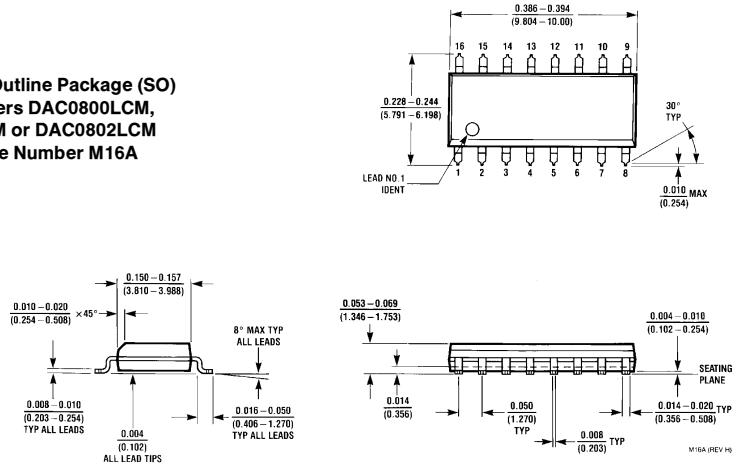
Physical Dimensions inches (millimeters)

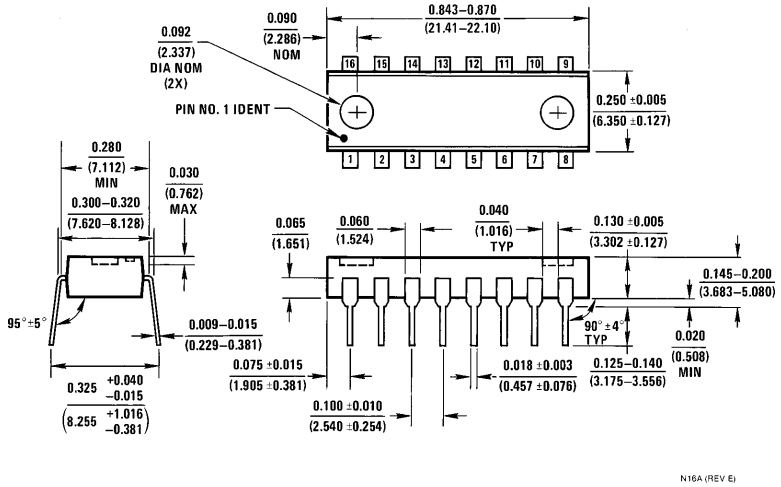


Molded Dual-In-Line Package
Order Numbers DAC0800 or DAC0802
NS Package Number J16A

Physical Dimensions inches (millimeters) (Continued)

Molded Small Outline Package (SO)
Order Numbers DAC0800LCM,
DAC0801LCM or DAC0802LCM
NS Package Number M16A





Molded Dual-In-Line Package
Order Numbers DAC0800, DAC0801, DAC0802
NS Package Number N16A

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